



512K x 8 SRAM

WITH OUTPUT ENABLE

FEATURES

OPTIONS

 Timing 20ns access

- High speed: 20, 25, 35 and 55ns
- High-performance, low-power, CMOS double-metal process

MARKING

-20

- Single +5V ±10% power supply
- Easy memory expansion with \overline{CE} and \overline{OE} options
- · All inputs and outputs are TTL compatible
- Fast Output Enable access time: 8ns

	25ns access	-25
	35ns access	-35
	55ns access	-55
•	Packages	
	Plastic SOJ (400 mil)	DJ
	Available in ceramic packages test specifications. Please refer to Micr <i>Book</i> .	,
•	2V data retention	L
•	Temperature	
	Industrial (-40°C to +85°C)	IT
	Automotive (-40°C to +125°C)	ΑT
	Extended (-55°C to +125°C)	XΤ

PIN ASSIGNMENT (Top View)

32-Pin SOJ (E-11)

A18	þ	1	32	b v∞
A16	Ц	2	31	A15
A14	ф	3	30	A17
A12	þ	4	29] WE
Α7	þ	5	28	A13
A6	þ	6	27	A8
A 5	þ	7	26	A9
A4	d	8	25	A11
А3		9	24) OE
A 2	ф	10	23	A10
A 1	þ	11	22) CE
Α0	þ	12	21	DQ8
DQ1	þ	13	20	DQ7
DQ2	C	14	19	DQ6
DQ3		15	18	DQ5
Vss	Д	16	17	DQ4

GENERAL DESCRIPTION

The Micron SRAM family employs high-speed, low-power CMOS designs using a four-transistor memory cell. Micron SRAMs are fabricated using double-layer metal, double-layer polysilicon technology.

For flexibility in high-speed memory applications, Micron offers chip enable (CE) capability. This enhancement can place the outputs in High-Z for additional flexibility in system design.

Writing to this device is accomplished when write enable (\overline{WE}) and \overline{CE} inputs are both LOW. Reading is accomplished when \overline{WE} remains HIGH while output enable (\overline{OE}) and \overline{CE} go LOW. The device offers a reduced power standby mode when disabled. This allows system designers to achieve their low standby power requirements.

All devices operate from a single +5V power supply and all inputs and outputs are fully TTL compatible.